



## Material Content Data Sheet



<b>Sales Product Name</b>		IPN80R3K3P7		<b>Issued</b>		1. August 2018			
<b>MA#</b>		MA001730340							
<b>Package</b>		PG-SOT223-3-1		<b>Weight*</b>		115.96 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.834	0.72	0.72	7194	7194	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135		
	non noble metal	iron	7439-89-6	0.052	0.05		452		
	non noble metal	copper	7440-50-8	52.304	45.11	45.17	451061	451648	
	non noble metal	copper	7440-50-8	0.160	0.14	0.14	1380	1380	
wire	non noble metal	copper	7440-50-8	0.160	0.14	0.14	1380	1380	
encapsulation	organic material	carbon black	1333-86-4	0.179	0.15		1545		
	plastics	epoxy resin	-	6.989	6.03		60268		
	inorganic material	silicondioxide	60676-86-0	52.563	45.32	51.50	453297	515110	
leadfinish	non noble metal	tin	7440-31-5	1.352	1.17	1.17	11660	11660	
plating	noble metal	silver	7440-22-4	0.220	0.19	0.19	1902	1902	
solder	non noble metal	tin	7440-31-5	0.026	0.02		222		
	noble metal	silver	7440-22-4	0.032	0.03		278		
	non noble metal	lead	7439-92-1	1.230	1.06	1.11	10606	11106	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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